

1200V, 70A,  $V_{ce(on)}$  = 2.5V Typical

# Ultra Fast NPT - IGBT®

The Ultra Fast NPT - IGBT<sup>®</sup> is a new generation of high voltage power IGBTs. Using Non-Punch-Through Technology, the Ultra Fast NPT-IGBT<sup>®</sup> offers superior ruggedness and ultrafast switching speed.

## **Features**

- Low Saturation Voltage
- Low Tail Current
- RoHS Compliant *M*

- Short Circuit Withstand Rated
- High Frequency Switching
- Ultra Low Leakage Current

Unless stated otherwise, Microsemi discrete IGBTs contain a single IGBT die. This device is recommended for applications such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).

#### MAXIMUM RATINGS

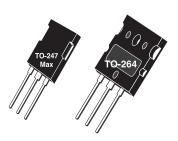
All Ratings:  $T_{c} = 25^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Ratings	Unit	
V <sub>ces</sub>	Collector Emitter Voltage	1200	- v	
$V_{GE}$	Gate-Emitter Voltage	±30		
I <sub>C1</sub>	Continuous Collector Current @ T <sub>c</sub> = 25°C	160		
I <sub>C2</sub>	Continuous Collector Current @ T <sub>c</sub> = 110°C	70	А	
I <sub>CM</sub>	Pulsed Collector Current ①	280		
SCWT	Short Circuit Withstand Time: $V_{ce}$ = 600V, $V_{ge}$ = 15V, $T_c$ = 125°C	10	μs	
P <sub>D</sub>	Total Power Dissipation @ $T_c = 25^{\circ}C$	961	W	
T_,T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to 150	*0	
TL	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	°C	

## STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage ( $V_{GE} = 0V$ , $I_{C} = 1.0$ mA)	1200			
V <sub>GE(TH)</sub>	Gate Threshold Voltage $(V_{CE} = V_{GE}, I_{C} = 2.5 \text{mA}, T_{j} = 25^{\circ}\text{C})$	3.5	5.0	6.5	) / - H -
V <sub>CE(ON)</sub>	Collector-Emitter On Voltage ( $V_{GE}$ = 15V, $I_{c}$ = 70A, $T_{j}$ = 25°C)		2.5	3.2	Volts
	Collector-Emitter On Voltage ( $V_{GE}$ = 15V, $I_{c}$ = 70A, $T_{j}$ = 125°C)		3.3		
	Collector-Emitter On Voltage ( $V_{GE}$ = 15V, $I_{c}$ = 140A, $T_{j}$ = 25°C)		3.5		
I <sub>ces</sub>	Collector Cut-off Current (V <sub>CE</sub> = 1200V, V <sub>GE</sub> = 0V, T <sub>j</sub> = 25°C) <sup>(2)</sup>		10	1000	μA
020	Collector Cut-off Current (V <sub>CE</sub> = 1200V, V <sub>GE</sub> = 0V, T <sub>j</sub> = 125°C) <sup>(2)</sup>		100		
I <sub>GES</sub>	Gate-Emitter Leakage Current (V <sub>GE</sub> = ±20V)			±250	nA

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.





#### **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min	Тур	Мах	Unit
C <sub>ies</sub>	Input Capacitance	Capacitance	i	7260		
C <sub>oes</sub>	Output Capacitance	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 25V f = 1MHz		643		рF
C <sub>res</sub>	Reverse Transfer Capacitance			199		
V <sub>GEP</sub>	Gate to Emitter Plateau Voltage	O sta Okanan	1	7.5		V
Q <sub>g</sub> 3	Total Gate Charge	Gate Charge		412	544	
Q <sub>ge</sub>	Gate-Emitter Charge	$V_{GE} = 15V$		48	62	
Q <sub>gc</sub>	Gate- Collector Charge	V <sub>CE</sub> = 600V I <sub>C</sub> = 70A		204	275	nC
t <sub>d(on)</sub>	Turn-On Delay Time	Inductive Switching (25°C)	1	33		
t,	Current Rise Time	V <sub>cc</sub> = 600V		48		
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GE</sub> = 15V		278		ns
t <sub>r</sub>	Current Fall Time	I <sub>с</sub> = 70А		64		
E <sub>on2</sub> 5	Turn-On Switching Energy	$R_{g} = 4.3 \Omega^{(4)}$		3816	5720	1
E <sub>off</sub>	Turn-Off Switching Energy	$T_{J} = +25^{\circ}C$		2582	3870	μJ
t <sub>d(on)</sub>	Turn-On Delay Time	Inductive Switching (125°C)		33		
t,	Current Rise Time	V <sub>cc</sub> = 600V		48		
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GE</sub> = 15V		320		ns
t <sub>r</sub>	Current Fall Time	I <sub>с</sub> = 70А		74		
E <sub>on2</sub> 5	Turn-On Switching Energy	$R_{g} = 4.3 \ \Omega^{(4)}$		5651	8475	
E <sub>off</sub>	Turn-Off Switching Energy	T_= +125°C		3323	4980	μJ

## THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic		Min	Тур	Max	Unit
R <sub>ejc</sub>	Junction to Case Thermal Resistance (IGBT)				.13	°C/W
R <sub>eja</sub>	Junction to Ambient Thermal Resistance				40	0/11
	Package Weight	B2		.22		oz
W <sub>T</sub>				6		g
		L		.36		oz
				10		g

1 Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

2 Pulse test: Pulse Width <  $380\mu s$ , duty cycle < 2%.

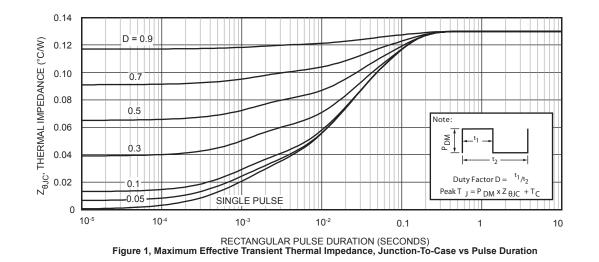
3 See Mil-Std-750 Method 3471.

4 R<sub>g</sub> is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

5 E<sub>on2</sub> is the clamped inductive turn on energy that includes a commutating diode reverse recovery current in the IGBT turn on energy loss. A combi device is used for the clamping diode.

6 E<sub>off</sub> is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1.

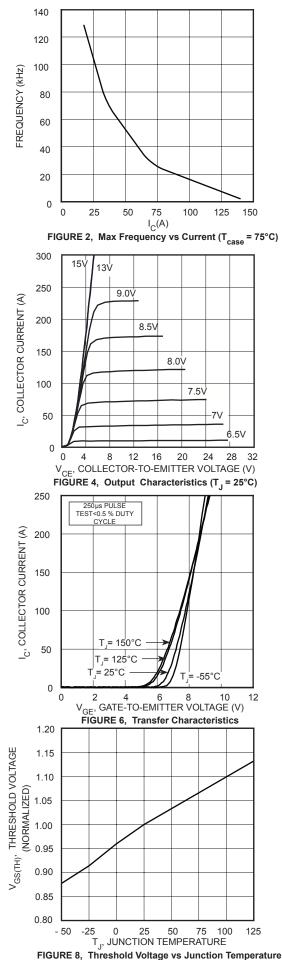
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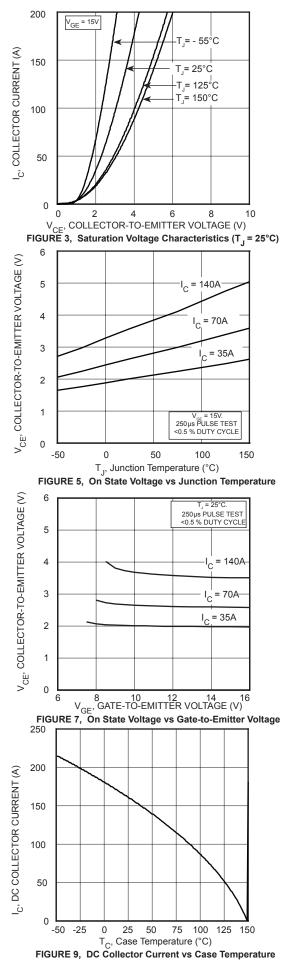


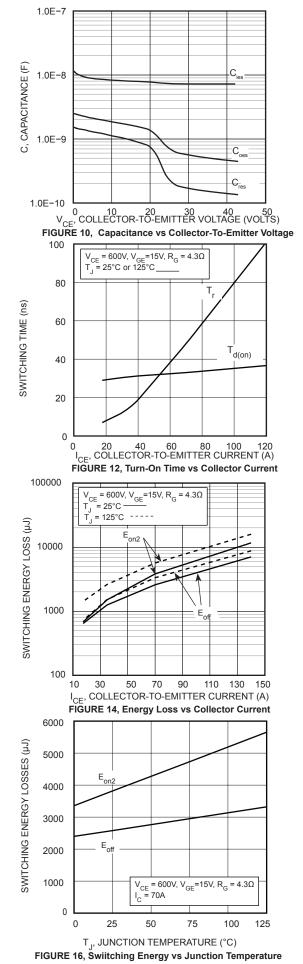
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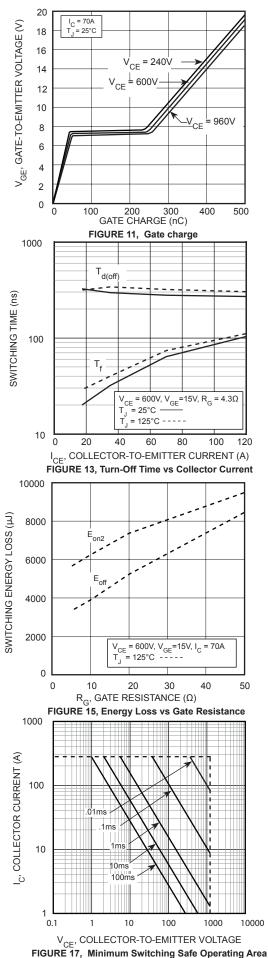
#### **TYPICAL PERFORMANCE CURVES**

APT70GR120B2\_L





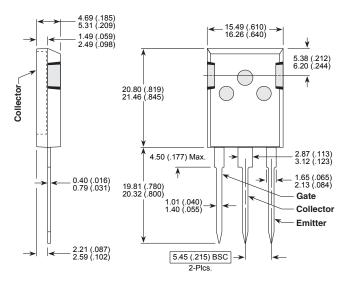




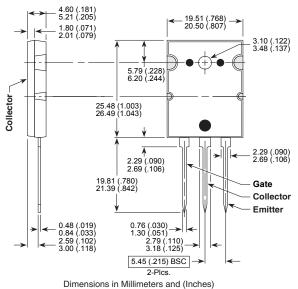








These dimensions are equal to the TO-247 without the mounting hole. Dimensions in Millimeters and (Inches)



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